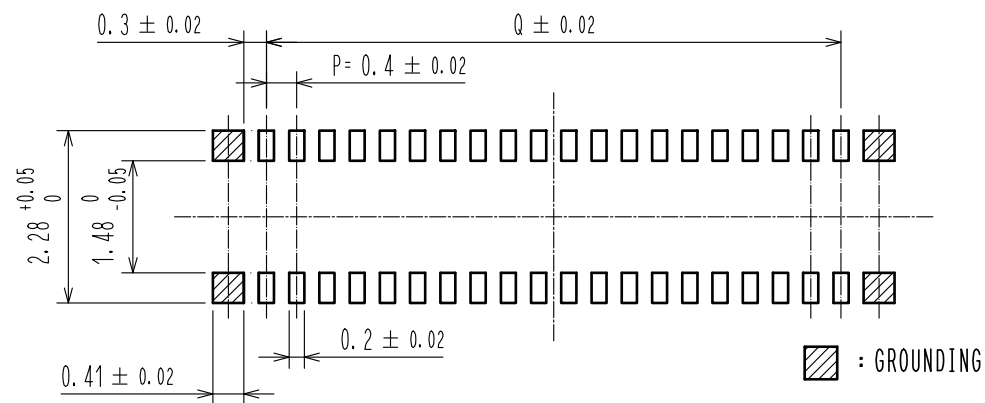
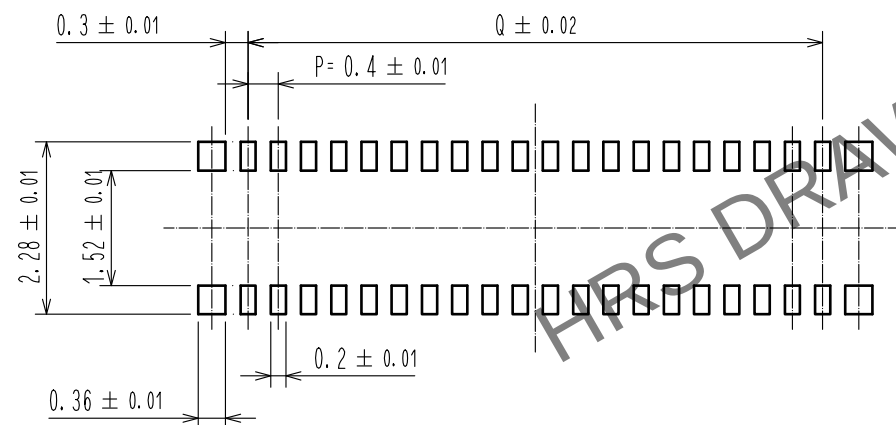


◆ RECOMMENDED PCB LAYOUT



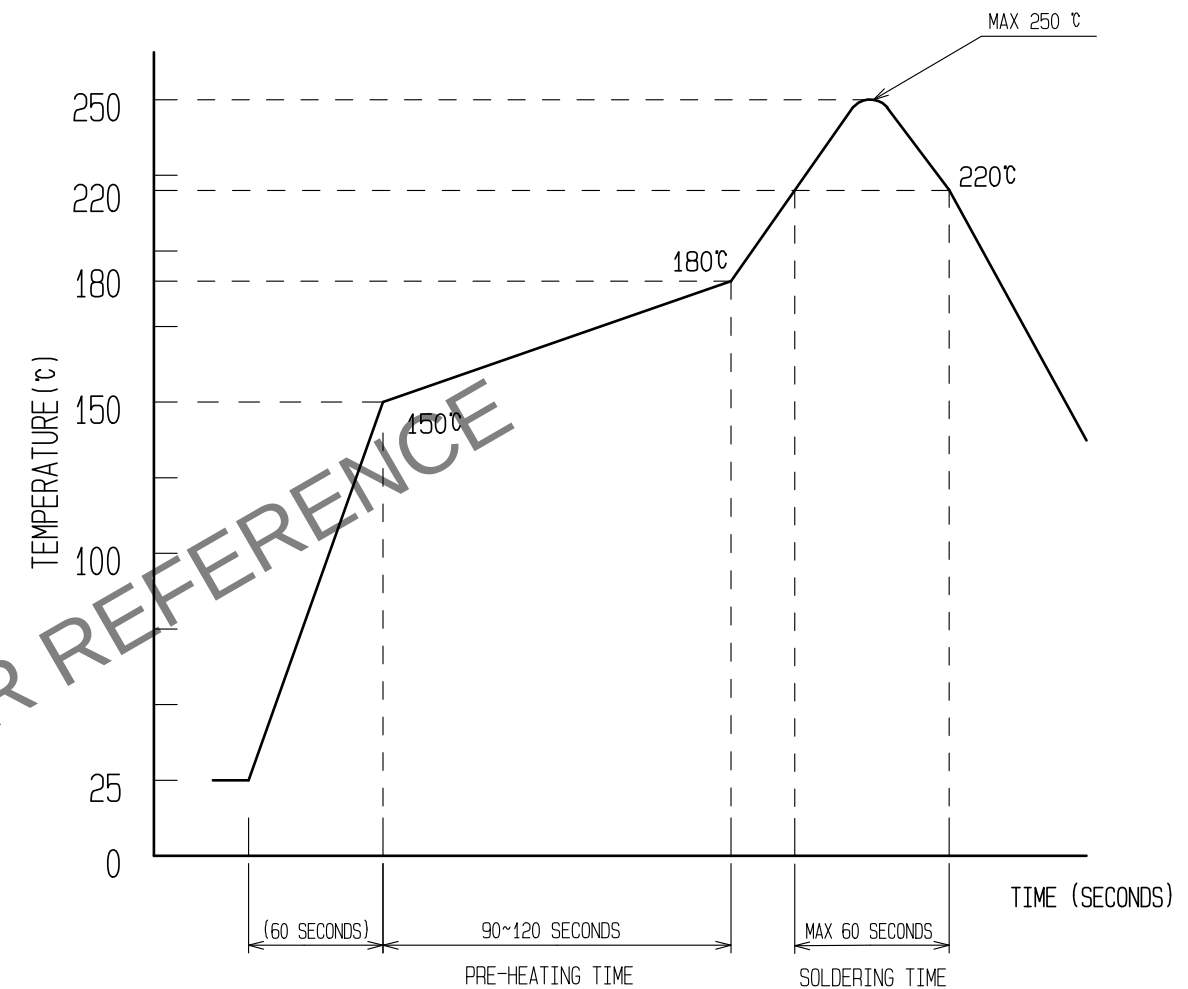
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μ m



PART No.	Q
BM14B(0.8)-10DS-0.4V(51)	1.6
BM14B(0.8)-12DS-0.4V(51)	2.0
BM14B(0.8)-20DS-0.4V(51)	3.6
BM14B(0.8)-22DS-0.4V(51)	4.0
BM14B(0.8)-24DS-0.4V(51)	4.4
BM14B(0.8)-30DS-0.4V(51)	5.6
BM14B(0.8)-34DS-0.4V(51)	6.4
BM14B(0.8)-40DS-0.4V(51)	7.6
BM14B(0.8)-50DS-0.4V(51)	9.6
BM14B(0.8)-60DS-0.4V(51)	11.6

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-322327-04
PART NO.	BM14B(0.8)-*DS-0.4V(51)
CODE NO.	CL684

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